

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants : Akihiko ENDO et al.

Confirmation No.: 1241

Appln. No. : 10/570,665
(U.S. National Stage of PCT/JP2004/013067)

Group Art Unit: 4158

Examiner: Ming Hung HUNG

I.A. Filed : September 8, 2004

For : BONDED WAFER AND ITS MANUFACTURING METHOD

AMENDMENT UNDER 37 C.F.R § 1.111

Commissioner of Patents
U.S. Patent and Trademark Office
Customer Service Window, Mail Stop Amendment
Randolph Building
401 Dulany Street
Alexandria, VA 22314

Sir:

Responsive to the Office Action mailed April 8, 2008, Applicants respectfully request reconsideration and withdrawal of the rejections of record in view of the following amendments and remarks. Inasmuch as the Office Action sets a three-month shortened statutory period for response, to expire on July 8, 2008, Applicants timely file this response and believe a Request for Extension of Time is not necessary. However, if any fees are necessary to maintain the pendency of this application, the Office is authorized to charge such fee to Deposit Account No. 19-0089.

Amendments to the Specification begins on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims, which begins on page 5 of this paper.

Remarks begin on page 8 of this paper.